

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

ENDPOINT DETECTION IN CHEMICAL-MECHANICAL
POLISHING OF PATTERNED WAFERS HAVING A LOW PATTERN
DENSITY

Application Number :

Confirmation Number:

First Named Applicant: Xinhui Wang

Attorney Docket Number: FIS920030031

Art Unit:

Examiner:

Search string: (6176765 or 6291351 or 6440263).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6176765	2001-01-23	Li et al.			
	2	6291351	2001-09-18	Li et al.			
	3	6440263	2002-08-27	Li et al.			

Signature

Examiner Name	Date